

FASTSTAR

FASTSTAR DU9721

High-Speed, High-Precision Die Bonder

DU9721 is a high-speed, high-precision die bonder designed for multi-chip packaging, delivering a placement accuracy of $\pm 7\mu\text{m}@3\sigma$. Featuring an open architecture and modular design, it delivers a maximum UPH up to 1500. The system supports dispensing, auto nozzle change, various wafer sizes, and process expansions, compatible with SIP and UV curing processes, it enables fast bonding and flexible process switching to meet complex packaging requirements.



Key Features



High Precision

Equipped with a high-magnification vision system, precision motion platform, thermal drift compensation, and closed-loop force control, achieving $\pm 7\mu\text{m}$ bonding accuracy.



High Flexibility

Compatible with 8–12" wafers, chip size range from 0.5 to 5 mm; supports multiple processes including dispensing, SIP, and UV curing.



High Efficiency

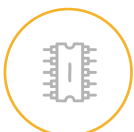
Optimized system structure delivers placement efficiency up to 1500 UPH. Supports auto calibration, dispensing compensation, and process optimization for rapid response.



High Adaptability

Modular platform design with quick-exchange feeding system; supports customized development and process upgrades to meet diverse production needs.

Applications



IC Chips



Electronic Modules



Power Devices



Technical Specifications

DU9721

Bonding Process		Dispensing/UV Bonding & Curing
Application		Die attach/RCAM/FCAM/VCM
Placement Accuracy		$\pm 7\mu\text{m}@3\sigma$ (Standard Die)
Angular Accuracy		$\pm 0.2^\circ$ (Standard Die)
Equipment Efficiency		1500UPH (Depending on process)
Dimensions		1346mmx1426mmx2130mm (L x W x H)
Weight		2300kg
Ambient Temperature		$23\pm 2^\circ\text{C}$
Bonding System	X/Y/Z	Repeatability: $\pm 1\mu\text{m}$
	Rotary Axis	Travel: 360° ; Repeatability: $\pm 0.15^\circ$
	Chip size	0.5x0.5mm-5x5mm
	Nozzle	Auto nozzle changer, up to 6 nozzles
	Bonding Force	(10g-100g) $\pm 2\text{g}$; (100g-500g) $\pm 3\%$
Loading/Unloading System	Standard Configuration	Supports 8"/12" wafers, 6"x6" gelpacks, waffle packs, etc.
	Standard Configuration	Inline automatic feeding system
	Substrate Size Compatibility	Length: 160–250 mm, Width: 55–100 mm
	Optional Configurations	Buffer unloading, UV curing, UV dipping, dispensing, barcode scanning
Vision System	Lighting	Each camera equipped with programmable 4-channel lighting (high-brightness point light + RGB ring light)
Facility Requirements	Power Supply	AC220V50/60HZ4.4KVA
	Compressed Air	0.5-0.7Mpa, 100L/min



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